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DEVICE AND METHOD FOR REGULATING APPLICATION OF ADHESIVES AND/OR SEALANTS

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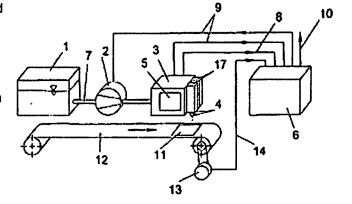
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Abstract of **DE10141676**

The invention relates to a device for the regulated application of adhesives and sealants to support materials (11), containing essentially the following components: a) a supply container for at least one adhesive and/or sealant (1), b) a delivery pump (2), c) an applicator head (3) comprising at least one applicator nozzle (4), d) a volume flow sensor (5) and e) a control unit (6) with an associated data processing programme. The supply container (1), the delivery pump (2) and the applicator head (3) with the at least one applicator nozzle (4) are interconnected by a distribution system (7) which conducts the adhesive and/or sealant (7). The volume flow sensor (5) and the control unit (6) with the associated data processing programme are interconnected by an impulse transmission line (8) and the control unit (6) with the associated data processing programme, the delivery pump (2) and the applicator head (3) are interconnected by control lines (9). The invention also relates to the use of this device and to a method using the device for the regulated application of adhesives and/or sealants to support materials. The invention is especially characterised in that the precise and constant application and metering of adhesives and/or sealants is made possible on a manufacturing scale.



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